

IRF7473TRPBF-VB Datasheet N-Channel 100 V (D-S) MOSFET

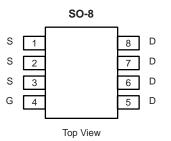
PRODUCT SUMMARY				
V _{DS}	100	V		
$R_{DS(on)}$ $V_{GS} = 10$ V	32	mΩ		
I _D	9	А		
Configuration	Single			

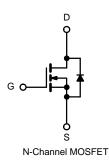
FEATURES

- Halogen-free According to IEC 61249-2-21
 Definition
- Extremely Low Q_{gd} for Switching Losses
- 100 % R_g Tested
- 100 % Avalanche Tested
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

• Primary Side Switch





Parameter		Symbol Limit		Unit	
Drain-Source Voltage		V _{DS}	100	V	
Gate-Source Voltage		V _{GS}	± 20	v	
Continuous Drain Current (T _J = 150 °C)	_	T _C = 25 °C		9	
	T _C = 70 °C		6		
	T _A = 25 °C	I _D	6 ^{b, c}		
	T _A = 70 °C		5 ^{b, c}	Α	
Pulsed Drain Current		I _{DM}	40	A	
Continuous Source-Drain Diode Current	T _C = 25 °C		7		
	T _A = 25 °C	ا _S	3.8 ^{b, c}		
Single Pulse Avalanche Current L = 0.1 mH		I _{AS}	30		
Single Pulse Avalanche Energy		E _{AS}	112	mJ	
Maximum Power Dissipation	T _C = 25 °C		14		
	T _C = 70 °C		5	w	
	$T_{A} = 25 \text{ °C}$	P _D	4 ^{b, c}	vv	
	T _A = 70 °C	1	2 ^{b, c}		
Operating Junction and Storage Temperature Range		T _J , T _{stq}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient ^{b, †}	t ≤ 10 s	R _{thJA}	33	40	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	17	21	C/W		

Notes:

a. Based on T_C = 25 °C.

b. Surface mounted on 1" x 1" FR4 board.

c. t = 10 s.

d. Maximum under steady state conditions is 80 °C/W.



RoHS COMPLIANT HALOGEN FREE Available



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static					<u> </u>	•
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA	100			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	1 250 4		172		~\//°C
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 10		mV/°C
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$	1.0		3.0	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA
Zara Cata Valtaga Drain Current		V _{DS} = 100 V, V _{GS} = 0 V			1	
Zero Gate Voltage Drain Current	IDSS	$V_{DS} = 100 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 55 \text{ °C}$			10	μΑ
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 10 \text{ V}, V_{GS} = 10 \text{ V}$	30			Α
Drain-Source On-State Resistance ^a	P	V _{GS} = 10 V, I _D = 5 A		32		
Diam-Source On-State Resistance	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 5 \text{ A}$		33		mΩ
Forward Transconductance ^a	g _{fs}	V _{DS} = 15 V, I _D = 5 A		20		S
Dynamic ^b						
Input Capacitance	C _{iss}			1900		pF
Output Capacitance	C _{oss}	$V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V}, \text{ f} = 1 \text{ MHz}$		150		
Reverse Transfer Capacitance	C _{rss}			50		
Total Gate Charge	Q _g	$V_{DS} = 75$ V, $V_{GS} = 10$ V, $I_{D} = 5$ A		28.5	43	
				23	35	nC
Gate-Source Charge	Q _{gs}	$V_{DS} = 75 \text{ V}, V_{GS} = 8 \text{ V}, I_{D} = 5 \text{ A}$		8		
Gate-Drain Charge	Q _{gd}			6.5		
Gate Resistance	R _g	f = 1 MHz		0.80	1.3	Ω
Turn-on Delay Time	t _{d(on)}			14	21	
Rise Time	t _r	V_{DD} = 50 V, R_L = 10 Ω		12	18	
Turn-Off Delay Time	t _{d(off)}	${\sf I}_{\sf D}\cong$ 5 A, ${\sf V}_{\sf GEN}$ = 10 V, ${\sf R}_{\sf g}$ = 1 Ω		22	33	
Fall Time	t _f			6	10	ns
Turn-On Delay Time	t _{d(on)}			16	24	115
Rise Time	t _r	V_{DD} = 50 V, R_L = 10 Ω		12	18	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 5 \text{ A}, \text{ V}_{\text{GEN}} = 8 \text{ V}, \text{ R}_g = 1 \Omega$		20	30	
Fall Time	t _f			7	12	
Drain-Source Body Diode Characteristi	cs					
Continuous Source-Drain Diode Current	۱ _S	T _C = 25 °C			7.7	A
Pulse Diode Forward Current ^a	I _{SM}				50	A
Body Diode Voltage	V _{SD}	I _S = 2.6 A		0.77	1.2	V
Body Diode Reverse Recovery Time	t _{rr}			63	95	ns
Body Diode Reverse Recovery Charge	Q _{rr}	I _F = 5 A, dl/dt = 100 A/μs, T _J = 25 °C		110	165	nC
Reverse Recovery Fall Time	t _a	$I_{\rm F} = 5$ A, ui/ul = 100 A/µs, $I_{\rm J} = 25$ °C		49		
Reverse Recovery Rise Time	t _b			14		ns

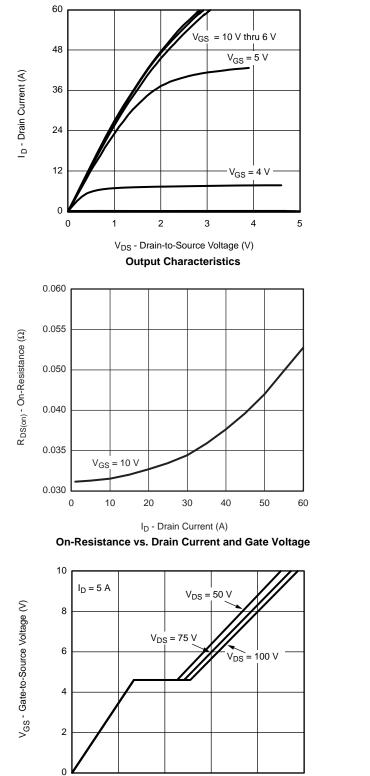
Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %

a. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

服务热线:400-655-8788

0

6

12

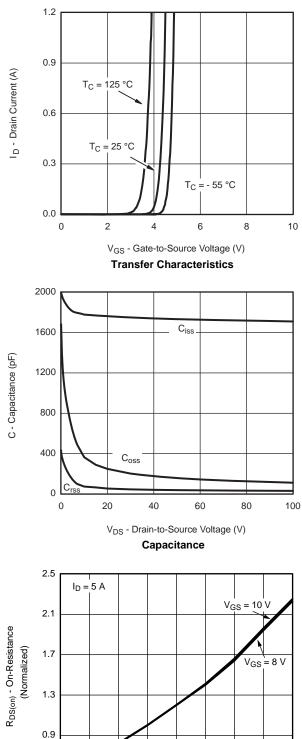
Qg - Total Gate Charge (nC)

Gate Charge

18

24

30



0.5

- 50

- 25

0

25

50

T_J - Junction Temperature (°C)

On-Resistance vs. Junction Temperature

75

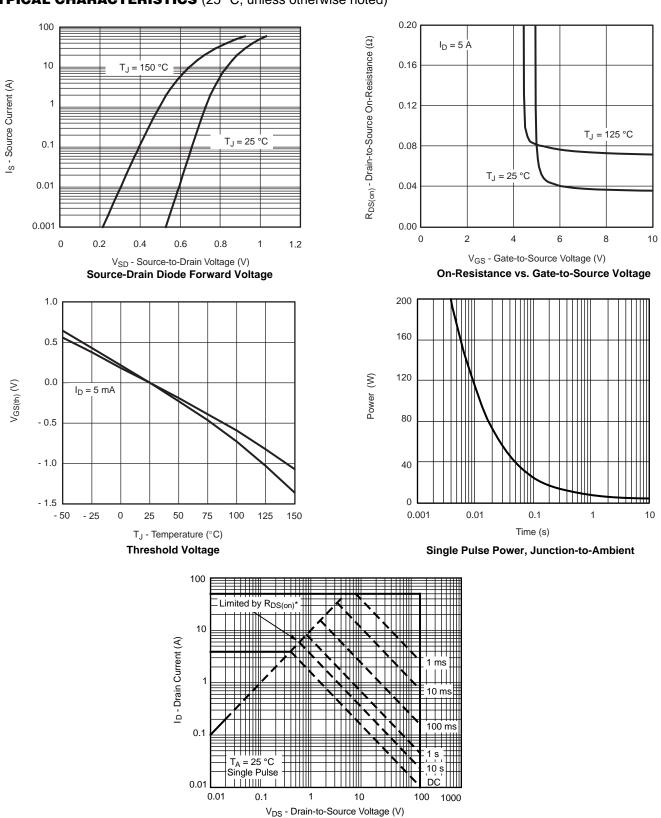
100

3

125

150



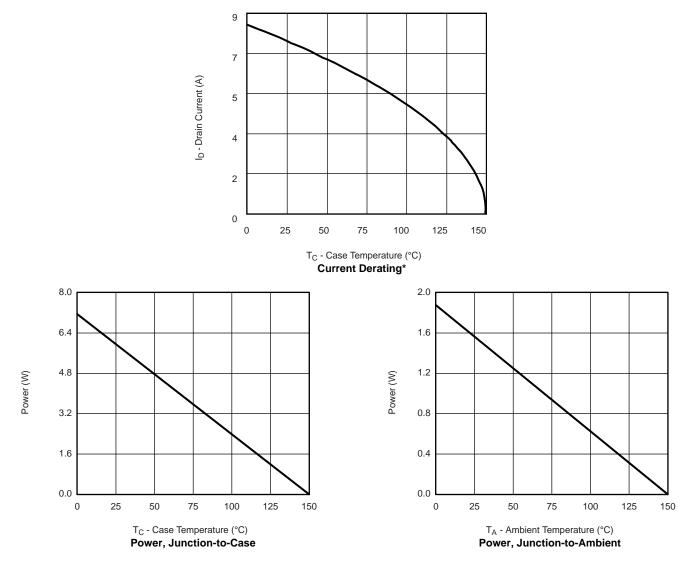


* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified Safe Operating Area, Junction-to-Ambient

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



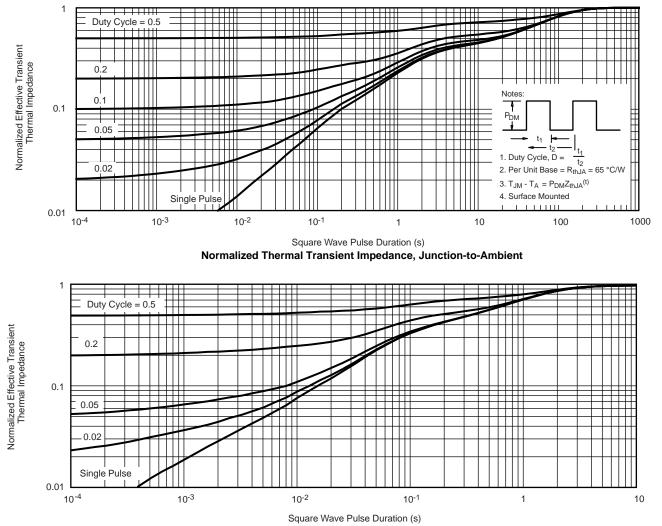
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



* The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



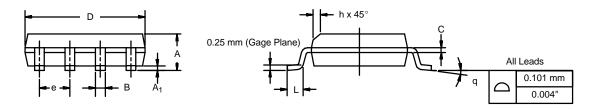
Normalized Thermal Transient Impedance, Junction-to-Foot



SOIC (NARROW): 8-LEAD

JEDEC Part Number: MS-012

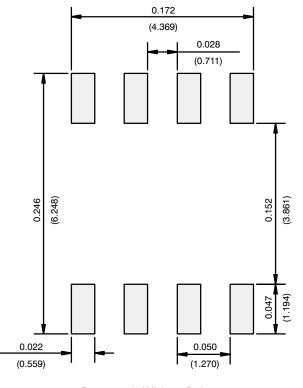




	MILLIMETERS		INC	HES	
DIM	Min	Max	Min	Max	
A	1.35	1.75	0.053	0.069	
A ₁	0.10	0.20	0.004	0.008	
В	0.35	0.51	0.014	0.020	
С	0.19	0.25	0.0075	0.010	
D	4.80	5.00	0.189	0.196	
E	3.80	4.00	0.150	0.157	
е	1.27	BSC	0.050 BSC		
н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.020	
L	0.50	0.93	0.020	0.037	
q	0°	8°	0°	8°	
S	0.44	0.64	0.018	0.026	
ECN: C-06527-Rev. I, 11-Sep-06 DWG: 5498					



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)



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